

## ABSTRACT

A method of manufacture of a semiconductor device comprises a step of providing an adhesive (30) between a semiconductor chip (20) and a substrate (10), a step of positioning electrodes (22) and leads (12) to oppose each other, and a step of applying pressure in the direction of making the gap between the semiconductor chip (20) and substrate (10) narrower, and on the substrate (10), in a region opposing the surface of the semiconductor chip (20) and avoiding the leads (12), a film (14) is formed with lower adhesion with the adhesive (30) than the substrate (10).

[illegible]